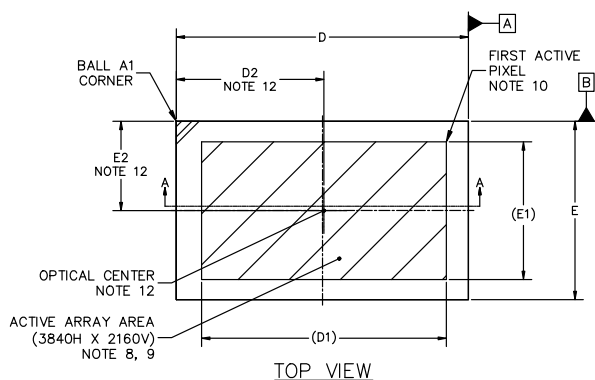


ODCSP59 6.41x3.91x0.63, 0.50P

CASE 570AY  
ISSUE A

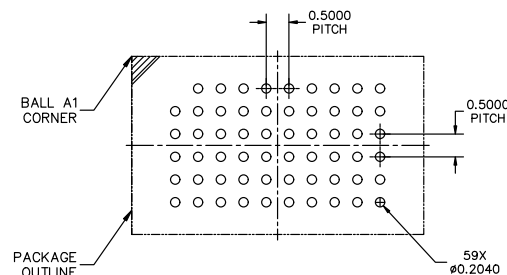
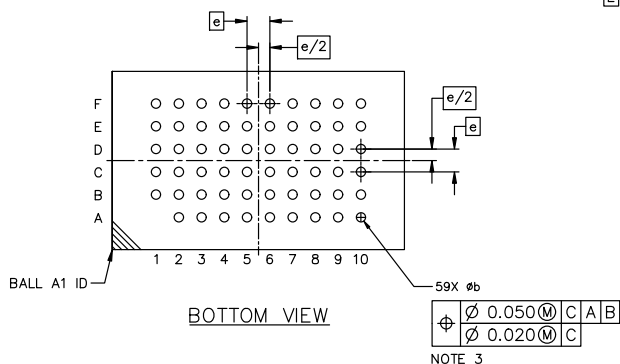
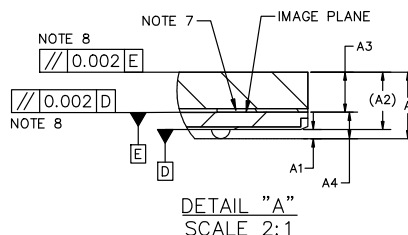
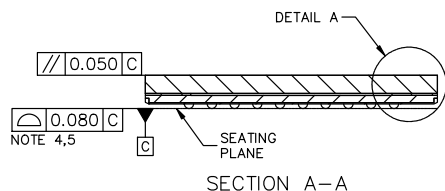
DATE 05 JUN 2025



NOTES:

1. DIMENSIONING AND TOLERANCING CONFORM TO ASME Y14.5-2018.
2. ALL DIMENSION ARE IN MILLIMETERS.
3. SOLDER BALL DIAMETER IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER PARALLEL TO DATUM C.
4. COPLANARITY APPLIES TO THE SPHERICAL CROWNS OF THE SOLDER BALLS.
5. DATUM C, THE SEATING PLANE IS DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
6. GLASS: 0.400 THICKNESS; REFRACTIVE INDEX = 1.52.
7. AIR GAP BETWEEN GLASS AND PIXEL ARRAY: 0.040 THICKNESS.
8. PARALLELISM APPLIES ONLY TO THE ACTIVE ARRAY.
9. MAXIMUM ROTATION OF ACTIVE ARRAY RELATIVE TO DATUMS A AND B IS  $\pm 0.1^\circ$ .
10. REFER TO THE DEVICE DATA SHEET FOR TOTAL PIXEL ARRAY DEFINITIONS.
11. PACKAGE CENTER (X, Y) = (0.000, 0.000).
12. OPTICAL CENTER RELATIVE TO PACKAGE CENTER (X, Y) = (0.035, -0.005).
13. PLAIN COVER GLASS WITHOUT AR COATING.

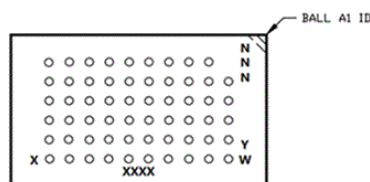
DIM	MILLIMETERS		
	MIN.	NOM.	MAX.
A	----	----	0.762
A1	0.081	0.101	0.121
A2	0.631 REF		
A3	0.425	0.440	0.455
A4	0.252	0.292	0.332
b	0.184	0.204	0.224
D	6.392	6.417	6.442
D1	5.376 REF		
D2	3.218	3.243	3.268
E	3.889	3.914	3.939
E1	3.024 REF		
E2	1.937	1.962	1.987
e	0.500 BSC		



RECOMMENDED MOUNTING FOOTPRINT\*

\* For additional information on our Pb-Free strategy and soldering details, please download the onsemi Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

GENERIC  
MARKING DIAGRAM\*



XXXX = Specific Device Code  
Y = Year  
W = Work Week  
NNN = Serial Number

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "•", may or may not be present. Some products may not follow the Generic Marking.

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